

EXHIBIT 17

Exhibit 17: Exemplary Evidence of Infringement of U.S. Patent No. 11,071,207 by Apple A16 Products

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Each of the below-listed Accused Products comprises an Apple A16 processor, which infringes in accordance with the claim charts below.

Accused Products
iPhone 14 Pro iPhone 14 Pro Max

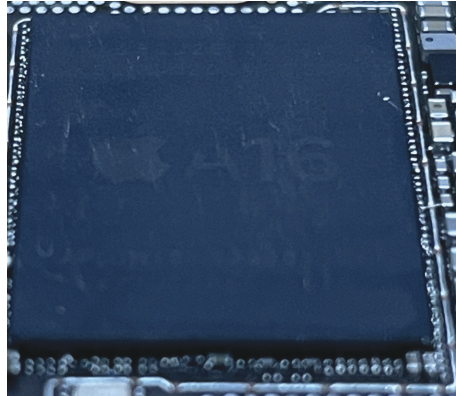
	Claim 1	Apple A16
1 pre	1. An electronic module, comprising:	The Apple A16 is an electronic module, comprising multiple electronic components including a semiconductor processor die and one or more capacitors.   Cross-section
1a	a first conductive-pattern layer and a second conductive-pattern layer disposed on the first conductive-pattern layer,	The Apple A16 comprises a first conductive-pattern layer and a second conductive-pattern layer disposed on the first conductive-pattern layer.

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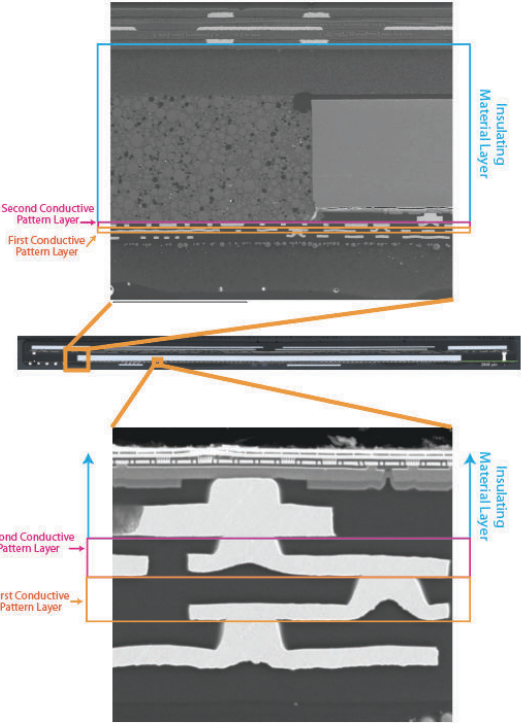
	Claim 1	Apple A16
		 The image displays two cross-sectional views of the Apple A16 chip. The top view shows a dark, textured surface with a blue box highlighting a specific region. Below this, a magnified view shows the layered structure of the chip. Labels with arrows point to the 'Second Conductive Pattern Layer' (indicated by a red dashed line), the 'First Conductive Pattern Layer' (indicated by an orange dashed line), and the 'Insulating Material Layer' (indicated by a blue dashed line). The bottom view shows a similar cross-section with a different pattern of conductive layers, also labeled with 'Second Conductive Pattern Layer', 'First Conductive Pattern Layer', and 'Insulating Material Layer'.
1b	the second conductive-pattern layer having a first surface;	The Apple A16's second conductive-pattern layer has a first surface.

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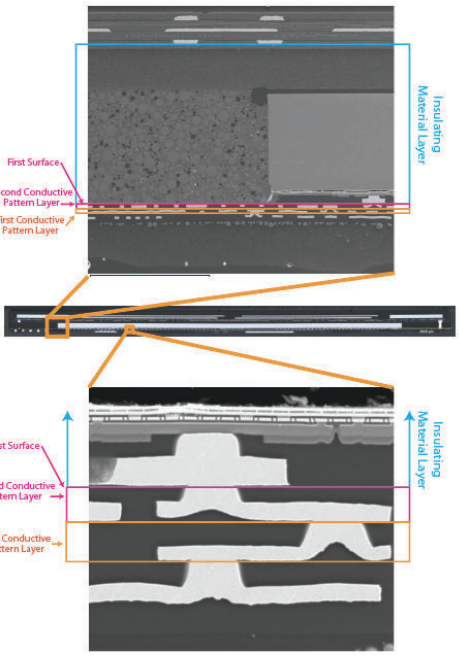
	Claim 1	Apple A16
		
1c	an insulating-material layer disposed on the first surface of the second conductive-pattern layer;	The Apple A16 comprises an insulating-material layer disposed on the first surface of the second conductive-pattern layer.

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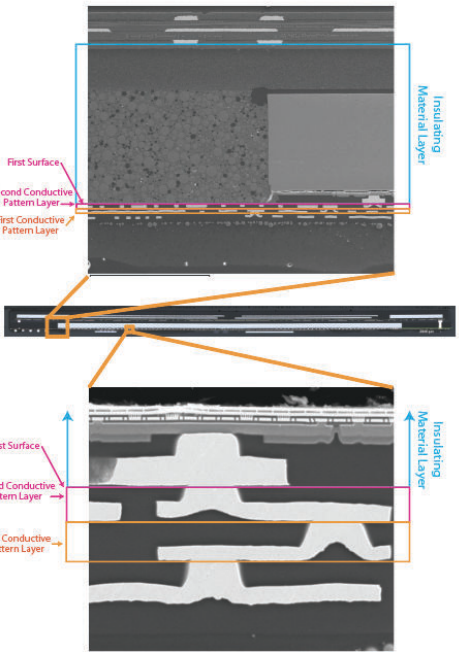
	Claim 1	Apple A16
		
1d	at least one installation cavity disposed in the insulating-material layer;	The Apple A16 comprises at least one installation cavity disposed in the insulating-material layer.

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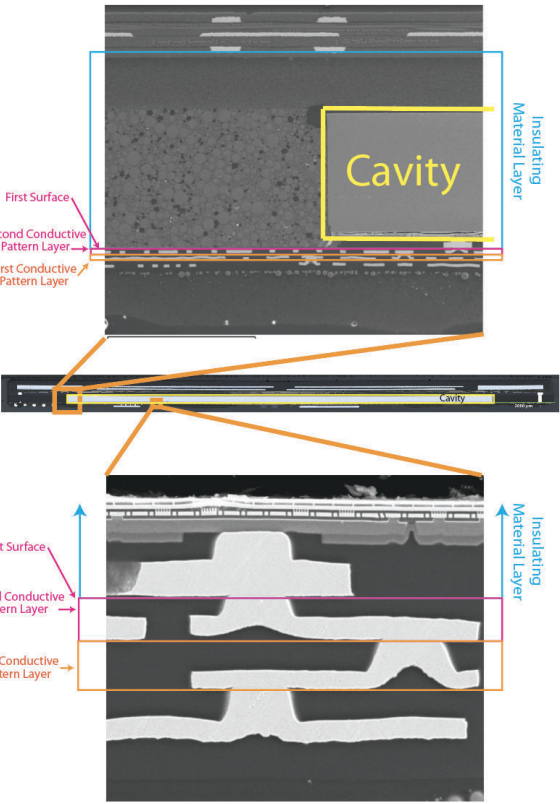
	Claim 1	Apple A16
		 The figure consists of three microscopic images of the Apple A16 chip. The top image is a top-down view showing a central 'Cavity' (yellow box) and an 'Insulating Material Layer' (blue box). Below the cavity, there are three horizontal layers: 'First Surface' (pink arrow), 'Second Conductive Pattern Layer' (pink arrow), and 'First Conductive Pattern Layer' (orange arrow). The middle image is a side-view cross-section of the chip, showing the 'Cavity' and the 'Insulating Material Layer'. The bottom image is a bottom-up view showing the 'First Surface' (pink arrow), 'Second Conductive Pattern Layer' (pink arrow), and 'First Conductive Pattern Layer' (orange arrow). The 'Insulating Material Layer' (blue arrow) is also indicated on the right side.
1e	a component disposed within the at least one installation cavity,	The Apple A16 comprises a component, for example an SoC die, disposed within the at least one installation cavity.

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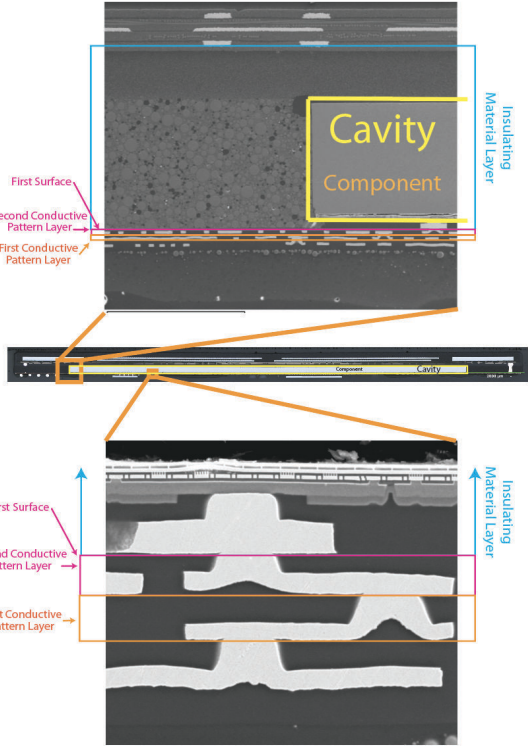
	Claim 1	Apple A16
		 The image displays three microscopic views of an Apple A16 component. The top view shows a dark surface with a yellow-outlined rectangular region labeled 'Cavity Component'. To the right of this region is a vertical blue line labeled 'Insulating Material Layer'. Below the top view is a horizontal cross-section showing a yellow-outlined rectangular region labeled 'Cavity'. To the left of this region is a vertical blue line labeled 'Insulating Material Layer'. The bottom view is a cross-section showing a white, irregularly shaped component. To the left of this component is a vertical blue line labeled 'Insulating Material Layer'. Labels with arrows point to specific layers: 'First Surface' (pink arrow), 'Second Conductive Pattern Layer' (pink arrow), and 'First Conductive Pattern Layer' (orange arrow).
1f	the component comprising contact zones comprising aluminum;	The A16 comprises components that comprise contact zones comprising aluminum.

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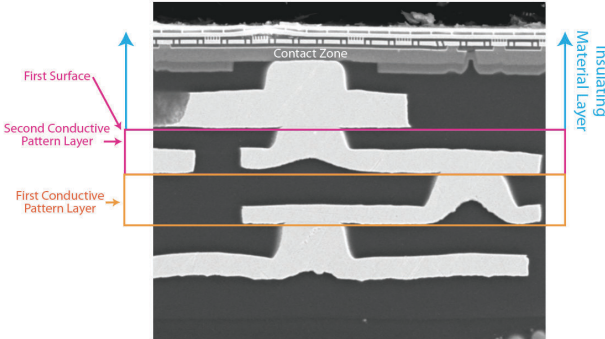
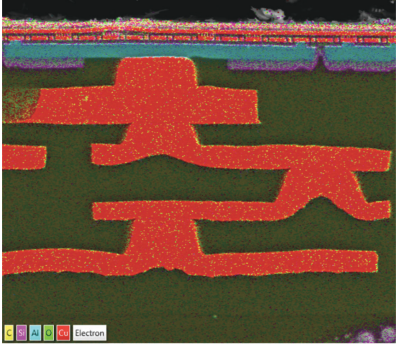
	Claim 1	Apple A16
		 
1g	first contact bumps disposed on the first surface of the second conductive-pattern layer, the first contact bumps electrically connected thereto; and	The Apple A16 comprises first contact bumps disposed on the first surface of the second conductive-pattern layer, the first contact bumps electrically connected thereto.

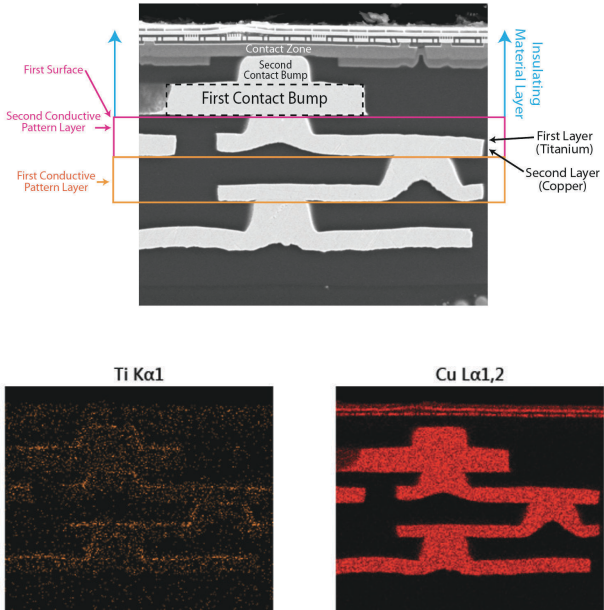
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	Claim 1	Apple A16
1h	second contact bumps disposed on the contact zones and electrically connected thereto,	The Apple A16 comprises second contact bumps disposed on the contact zones and electrically connected thereto.
1i	wherein at least one of the first conductive-pattern layer and the second conductive-pattern layer	In the Apple A16, at least one of the first conductive-pattern layer and the second conductive-pattern layer (in fact, both conductive pattern layers) comprises at least two layers of at least two different materials (e.g. titanium and copper).

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	Claim 1	Apple A16
	comprises at least two layers of at least two different materials.	 The diagram illustrates a cross-section of a contact structure. At the top is the 'First Surface'. Below it is the 'Second Conductive Pattern Layer', which contains a 'First Contact Bump' and a 'Second Contact Bump'. The 'First Contact Bump' is shown with a dashed outline. Below the pattern layer is the 'First Conductive Pattern Layer'. To the right, an 'Insulating Material Layer' is shown. The 'First Layer (Titanium)' is the top layer of the contact bump, and the 'Second Layer (Copper)' is the bottom layer. Below the cross-section are two elemental maps: 'Ti Kα1' showing the distribution of titanium and 'Cu Lα1,2' showing the distribution of copper. The copper map shows a distinct red pattern corresponding to the contact bumps.